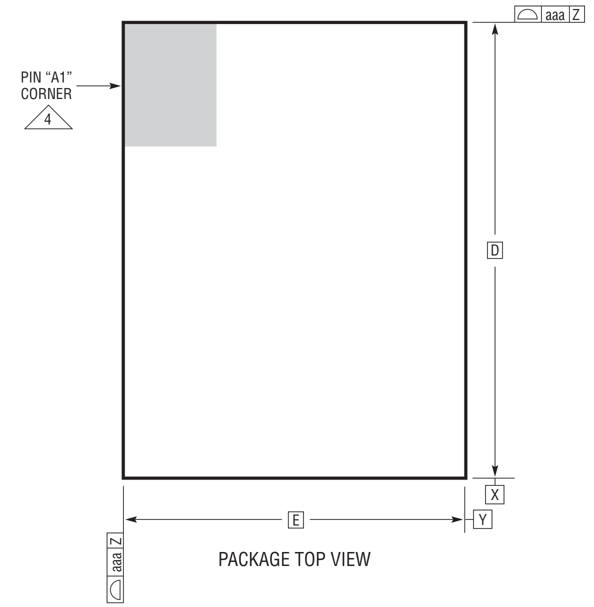
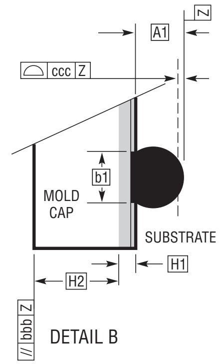
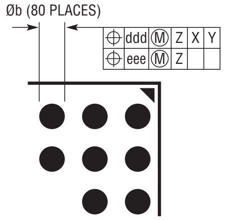
BGA Package
80-Lead (11.25mm × 9mm × 2.22mm)
(Reference LTC DWG # 05-08-1979 Rev A)



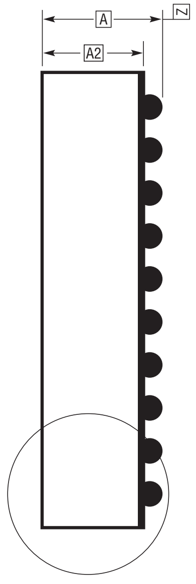
PACKAGE TOP VIEW



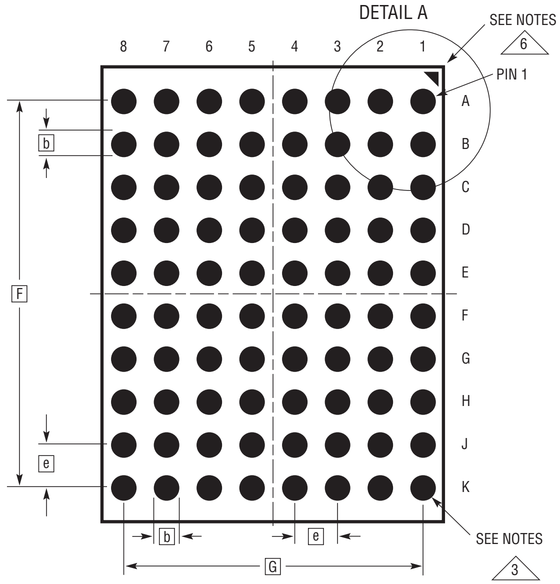
DETAIL B



DETAIL A



PACKAGE SIDE VIEW



PACKAGE BOTTOM VIEW

NOTES:

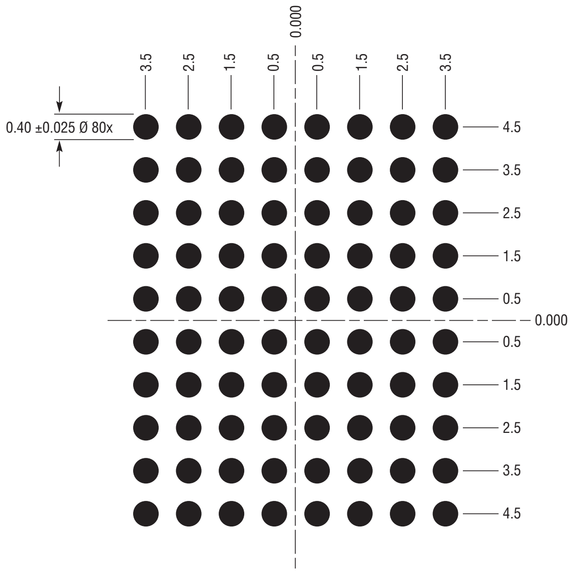
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS

3 BALL DESIGNATION PER JESD MS-028 AND JEP95

4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6 ⚠ PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

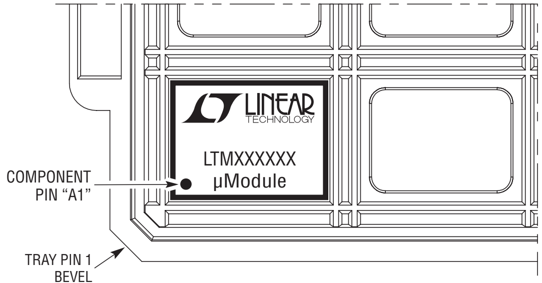


SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS

SYMBOL	MIN	NOM	MAX	NOTES
A	2.07	2.22	2.37	
A1	0.35	0.40	0.45	BALL HT
A2	1.72	1.82	1.92	
b	0.45	0.50	0.55	BALL DIMENSION
b1	0.35	0.40	0.45	PAD DIMENSION
D		11.25		
E		9.00		
e		1.00		
F		9.00		
G		7.00		
H1	0.27	0.32	0.37	SUBSTRATE THK
H2	1.45	1.50	1.55	MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	

TOTAL NUMBER OF BALLS: 80



PACKAGE IN TRAY LOADING ORIENTATION

BGA 80 0517 REV A